

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
1	IC301	1		TPD7104AF	TOSHIBA	Automotive High side power-MOSFET driver	PS-8		
2	IC302	1		MAX25432BATLG /V+	Analog Devices	DC-DC Controller			
3	Q301, Q302, Q307	3		XPN3R804NC	TOSHIBA	Automotive Nch MOSFET, 40 V, 40 A	TSOP Advance (WF)		
4	Q303, Q304, Q305, Q306	4		XSM6K519NW	TOSHIBA	Automotive Nch MOSFET, 40 V, 8 A	DFN 2020B (WF)		
5	D301	1		XCUZ5V6	TOSHIBA	Automotive Zener Diode, 5.6 V	USC		
6	D302, D307	2		Diode-150degC		Schottky Barrier Diode, 30 V, 200 mA, 150 degreeC		1.6 x 0.8 (0603)	
7	D308, D309	2		XCUZ16V	TOSHIBA	Automotive Zener Diode, 16 V	USC		
8	R301, R302, R315, R316, R329	5	0 Ω			1 A		1.6 x 0.8 (0603)	
9	R304, R305	2	3 m Ω			± 1 %, 1 W		3.2 x 6.4 (1225)	
10	R306	1	5 m Ω			± 1 %, 1 W		3.2 x 6.4 (1225)	
11	R310	1	2.4 k Ω			± 5 %, 250 mW		3.2 x 1.6 (1206)	
12	R317	1	10 Ω			± 5 %, 100 mW		1.0 x 0.5 (0402)	
13	R319	1	100 k Ω			± 5 %, 250 mW		2.0 x 1.2 (0805)	
14	R320	1	10 k Ω			± 5 %, 100 mW		1.0 x 0.5 (0402)	
15	R321, R322	2	4.7 k Ω			± 5 %, 100 mW		1.0 x 0.5 (0402)	
16	R323, R324, R327, R328, R330, R331, R332, R334, R337	9	0 Ω			1 A		1.0 x 0.5 (0402)	
17	R325	1	10 k Ω			± 5 %, 100 mW		1.0 x 0.5 (0402)	
18	R333	1	10 k Ω			± 1 %, 100 mW		1.0 x 0.5 (0402)	
19	R336	1	499 Ω			± 1 %, 100 mW		1.0 x 0.5 (0402)	
20	C301, C302, C315, C316	4	4.7 μ F			Ceramic, 35 V, ± 10 %		2.0 x 1.2 (0805)	
21	C303, C308, C313	3	10 μ F			Ceramic, 50 V, ± 10 %		3.2 x 2.5 (1210)	
22	C304, C321, C322, C339, C345, C346	6	1 μ F			Ceramic, 50 V, ± 10 %		1.6 x 0.8 (0603)	

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23	C307, C312	2	82 μ F	HHXJ500ARA820 MHA0G	CHEMI-CON	Aluminum Hybrid, 50 V, ± 20 %		8.3 x 8.3	
24	C309, C314, C317, C318, C320, C331, C240, C241	8	0.1 μ F			Ceramic, 50 V, ± 10 %		1.0 x 0.5 (0402)	
25	C319, C333, C337	3	0.01 μ F			Ceramic, 50 V, ± 10 %		1.0 x 0.5 (0402)	
26	C323, C329, C335	3	120 μ F	HHXJ350ARA121 MF80G	CHEMI-CON	Aluminum Hybrid, 35 V, ± 20 %		6.3 x 7.7	
27	C324, C327, C330, C332	4	10 μ F			Ceramic, 35 V, ± 10 %		3.2 x 1.6 (1206)	
28	C325, C338	1	10 μ F			Ceramic, 35 V, ± 10 %		2.0 x 1.2 (0805)	
29	C328	1	1 μ F			Ceramic, 35 V, ± 10 %		1.6 x 0.8 (0603)	
30	C334, C336	2	0.22 μ F			Ceramic, 50 V, ± 10 %		1.6 x 0.8 (0603)	
31	C334, C336	1	1 nF			Ceramic, 50 V, ± 20 %		2.0 x 1.2 (0805)	
32	C342	1	10 μ F			Ceramic, 16 V, ± 10 %		1.6 x 0.8 (0603)	
33	C343	1	4.7 μ F			Ceramic, 16 V, ± 10 %		1.6 x 0.8 (0603)	
34	C344, C347, C348, C351	4	100 pF			Ceramic, 50 V, ± 5 %		1.0 x 0.5 (0402)	
35	C352	1	0.012 μ F			Ceramic, 16 V, ± 10 %		1.0 x 0.5 (0402)	
36	C353	1	0.033 μ F			Ceramic, 10 V, ± 10 %		1.0 x 0.5 (0402)	
37	C354	1	0.047 μ F			Ceramic, 10 V, ± 10 %		1.0 x 0.5 (0402)	
38	L301	1	0.47 μ H	XEL4030-471MEC	Coilcraft	15.6 A, ± 20 %		4.0 x 4.0	
39	L302	1	10 μ H	XAL8080-103MED	Coilcraft	8.7 A, ± 20 %		8.1 x 8.6	
40	L303	1	0.22 μ H	IHLP1212BZEV2 2M5A	Vishay	8.35 A, ± 20 %		3.3 x 3.3	
41	FL301	1	30 Ω	MPZ1608S300AT	TDK	Ferrite Bead, 5 A, 30 Ω @ 100 MHz		1.6 x 0.8 (0603)	
42	CN301	1		HVH-280-2P-6_5DS	Hirose	Connector, 6.5 mm pitch, 2 positions			
43	CN302	1		502352-0501	Molex	Connector, 2 mm pitch, 5 positions			
44	CN303	1		502352-1000	Molex	Connector, 2 mm pitch, 10 positions			
45	D303, D304, D305, D306	4		CES520	TOSHIBA	Automotive Schottky Barrier Diode, 30 V, 200 mA	ESC		Not Mount

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
46	R303, R307, R308, R309, R311, R312, R313, R314	8	0 Ω			1 A		1.0 x 0.5 (0402)	Not Mount
47	R326, R335, R338, R339, R340, R341	6	10 k Ω			± 1 %, 100 mW		1.0 x 0.5 (0402)	Not Mount
48	C305, C306	2	0.1 μ F			Ceramic, 50 V, ± 10 %		1.6 x 0.8 (0603)	Not Mount
49	C310, C311	2	0.001 μ F			Ceramic, 50 V, ± 10 %		1.0 x 0.5 (0402)	Not Mount
50	C326	1	120 μ F	HHXJ350ARA121 MF80G	CHEMI-CON	Aluminum Hybrid, 35 V, ± 20 %		6.3 x 7.7	Not Mount
51	C349, C350	2	270 pF			Ceramic, 50 V, ± 10 %		1.0 x 0.5 (0402)	Not Mount
52	C355	1	0.1 μ F			Ceramic, 50 V, ± 10 %		1.0 x 0.5 (0402)	Not Mount

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